

**REMARKS**

Claims 2-4, 11-14, 16-19, and 21-23 are all the claims pending in the application. Claims 15 and 20 have been canceled without prejudice or disclaimer.

***Claim Rejections - 35 USC § 103***

Claims 2, 3, and 11-22 stand rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over U.S. Patent No. 5,727,310 to Casson *et al.* (“Casson”) in view of U.S. Patent No. 6,323,559 to Chan *et al.* (“Chan”), and further in view of U.S. Patent No. 6,670,559 to Centola *et al.* (“Centola”). Claim 23 stands rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Casson in view of Centola.

For *at least* the following reasons, Applicants respectfully traverse the rejection.

In order to expedite prosecution, Applicants amend independent claims 2, 11, 18, and 23 to recite, in some variation, that the anisotropic electrical conductor includes either a metal wire selected from a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire as electrically conductive material, or one of gold-plated particles, silver-plated particles, and copper-plated particles. Applicants respectfully submit that the alleged combination of Casson, Centola, and Chan does not render claim 1 unpatentable.

For example, Casson discloses a structure in which printed circuit boards are connected via an anisotropic conductive member, and shows a structure as a preferable example in which the anisotropic conductive member is a material in which a solder material is mixed as conductive particles into an insulating thermosetting resin. When connecting printed circuit boards via an anisotropic conductive member which uses a solder material as conductive

particles which are dispersed using a thermosetting resin as an adhesive, sufficient heating is necessary. Casson teaches a specific example of using a tin-lead eutectic solder having a melting point of 361°F (e.g., Casson, col. 12, lines 1 to 44).

Further, structures of the relevant printed circuit boards in Casson are completely combined with each other via the solder material by means of the thermosetting resin. Therefore, even if a problem occurs in the relevant unit, it is impossible to separate the connected printed circuit boards without damaging them.

In contrast, in the present invention as claimed, a metal wire (e.g., a gold wire, a copper wire, a brass wire, a phosphor bronze wire, a nickel wire, or a stainless wire) or metal-plated particles (e.g., gold-plated particles, silver-plated particles, or copper-plated particles) are included in the anisotropic electrical conductor, typically, embedded in a base such as Si rubber (i.e., non-adhesive insulating rubber). In the claimed circuit board unit in which no solder material is used, no heating is necessary for connecting the first substrate and the second substrate (e.g., printed circuit boards), and thus, the first substrate and the second substrate are not completely combined with each other. Instead, the first substrate and the second substrate are simply connected with each other. In other words, even if a problem occurs in the claimed circuit board unit, the first substrate and the second substrate can be easily separated from each other without damaging them.

Accordingly, the present invention as claimed having the above-described distinctive features could not have been anticipated by Casson, and does not relate to the structures of

Centola and Chan. Therefore, the present invention as claimed in claims 1, 11, 18, and 23 is patentable over Casson alone, or in combination with Centola and Chan.

Claims 3, 12-14, 16, 17, 19, 21, and 22 are patentable *at least* by virtue of their dependency.

Since claims 15 and 20 have been canceled, the rejection thereto is rendered moot.

***Conclusion***

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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CUSTOMER NUMBER

Date: September 15, 2008